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(12) **United States Design Patent**
Kondoh et al.

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(54) **TRANSFER-CHAMBER**

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(**) Term: **14 Years**

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(51) **LOC (8) Cl.** **15-09**

(52) **U.S. Cl.** **D15/144.1**

(58) **Field of Classification Search** D15/144,
D15/144.1, 144.2; 29/25.01; 62/55.5; 118/620,
118/719, 733; 165/1; 361/65; 392/416; 414/217,
414/416, 716, 786, 935-941; 204/298.11;
427/225, 248.1, 250

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a transfer-chamber, as shown and described.

DESCRIPTION

The present article relates to a transfer-chamber of a multi-chamber type semiconductor substrate processing apparatus for a film forming process and other processes for semiconductor substrates and others to be processed. A plurality of process chambers are provided around the transfer-chamber so as to transfer the substrate received from a load-lock chamber to, through a loader-module shown in a reference drawing illustrating a state of usage of the transfer-chamber, the process chambers by means of a vacuum arm provided in the transfer-chamber.

FIG. 1 is a front elevational view of the transfer-chamber;

FIG. 2 is a back elevational view thereof;

FIG. 3 is a top view thereof;

FIG. 4 is a bottom view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is 7—7 sectional view shown in FIG. 3.

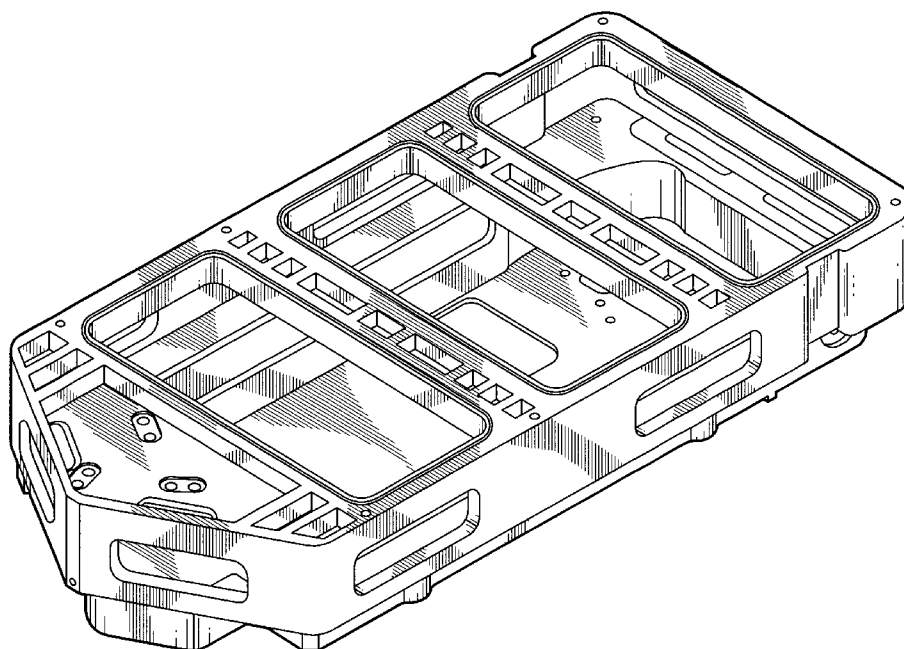
FIG. 8 is 8—8 sectional view shown in FIG. 3.

FIG. 9 is 9—9 sectional view shown in FIG. 5.

FIG. 10 is a perspective view thereof; and,

FIG. 11 is a reference figure showing a bottom perspective view thereof.

1 Claim, 8 Drawing Sheets



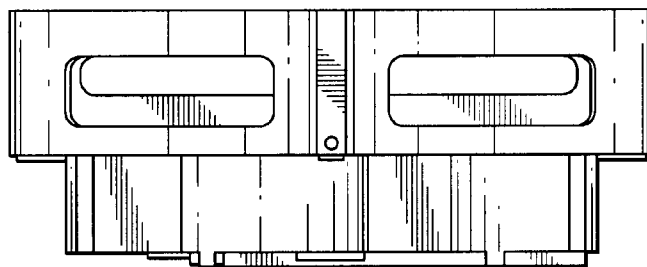


FIG. 1

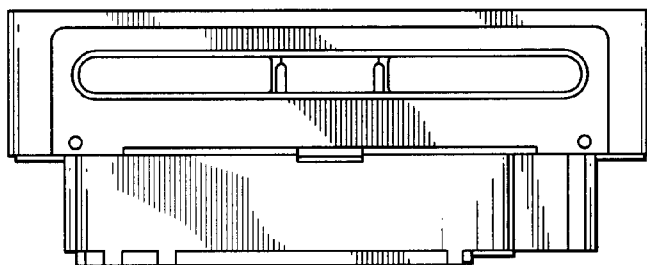


FIG. 2

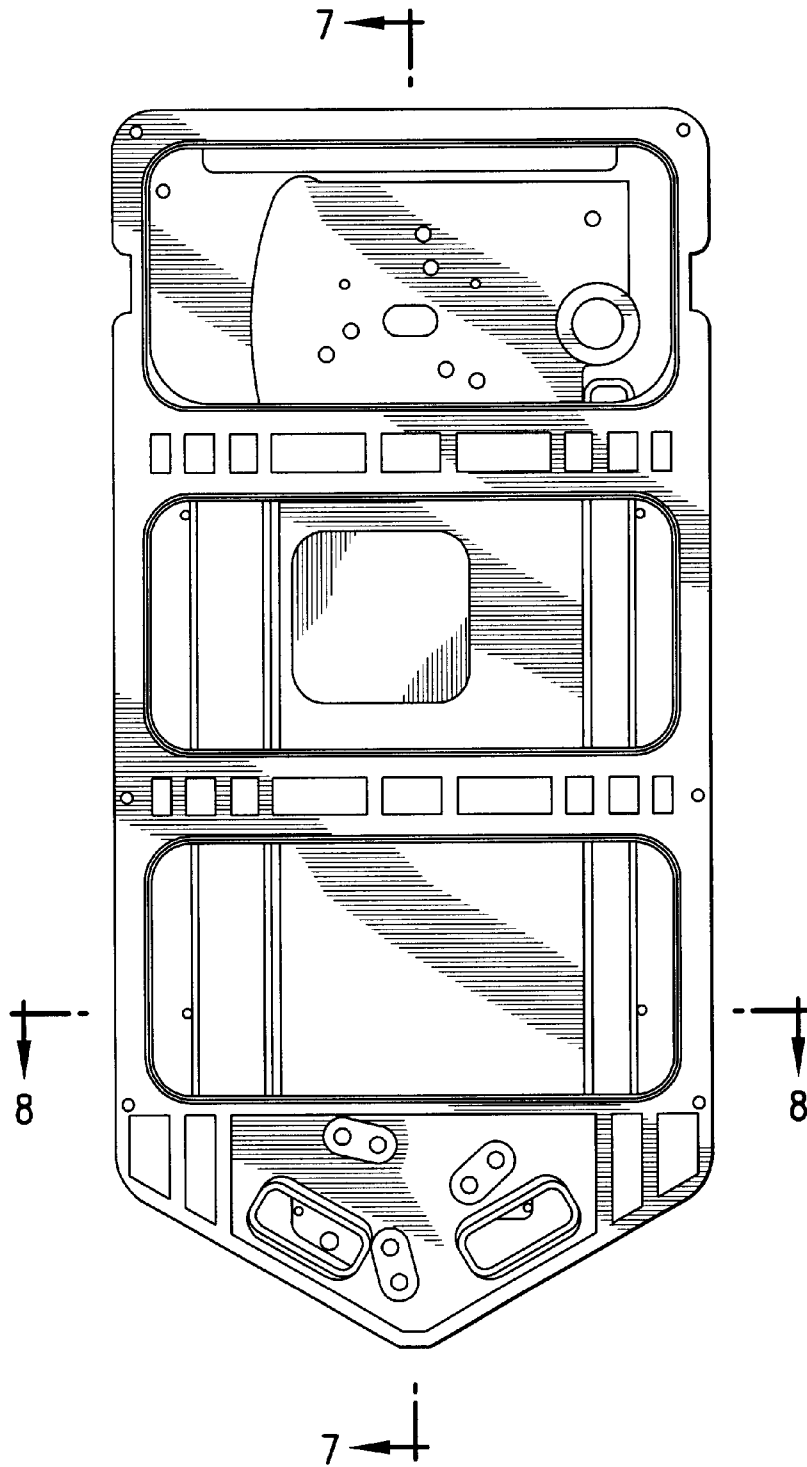


FIG. 3

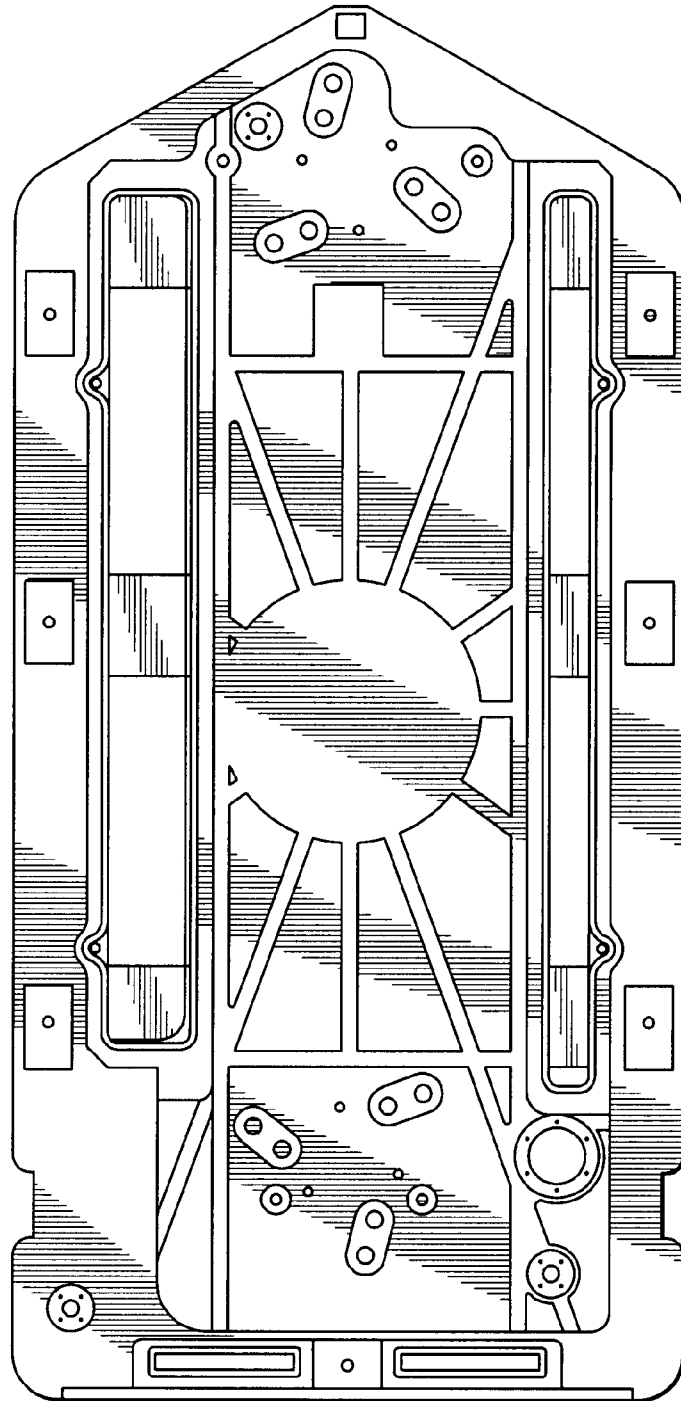


FIG.4

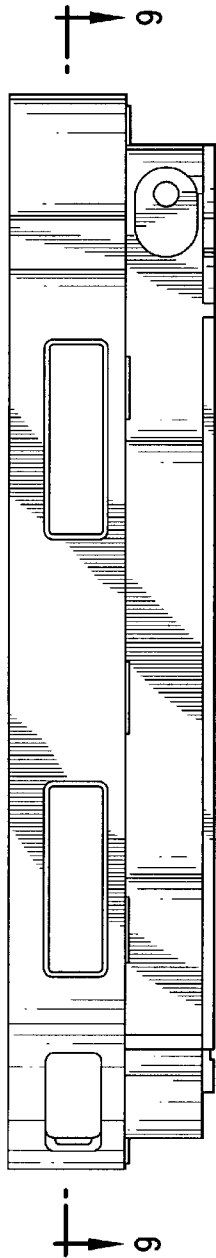


FIG. 5

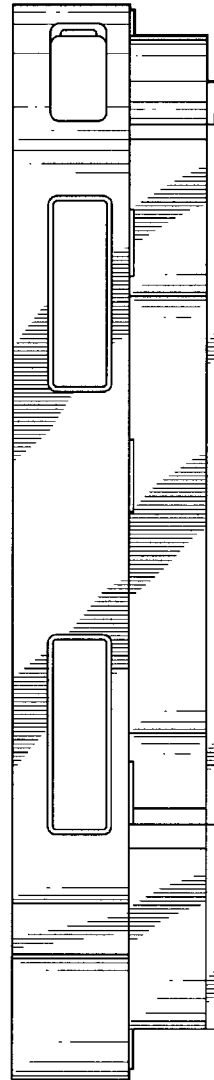


FIG. 6

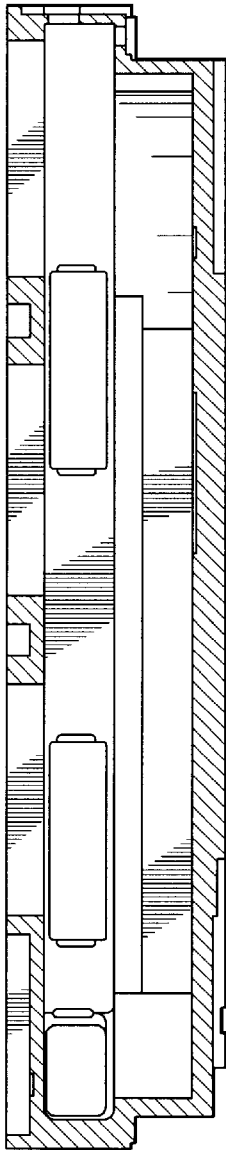


FIG. 7

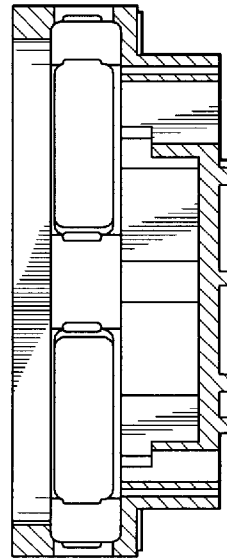


FIG. 8

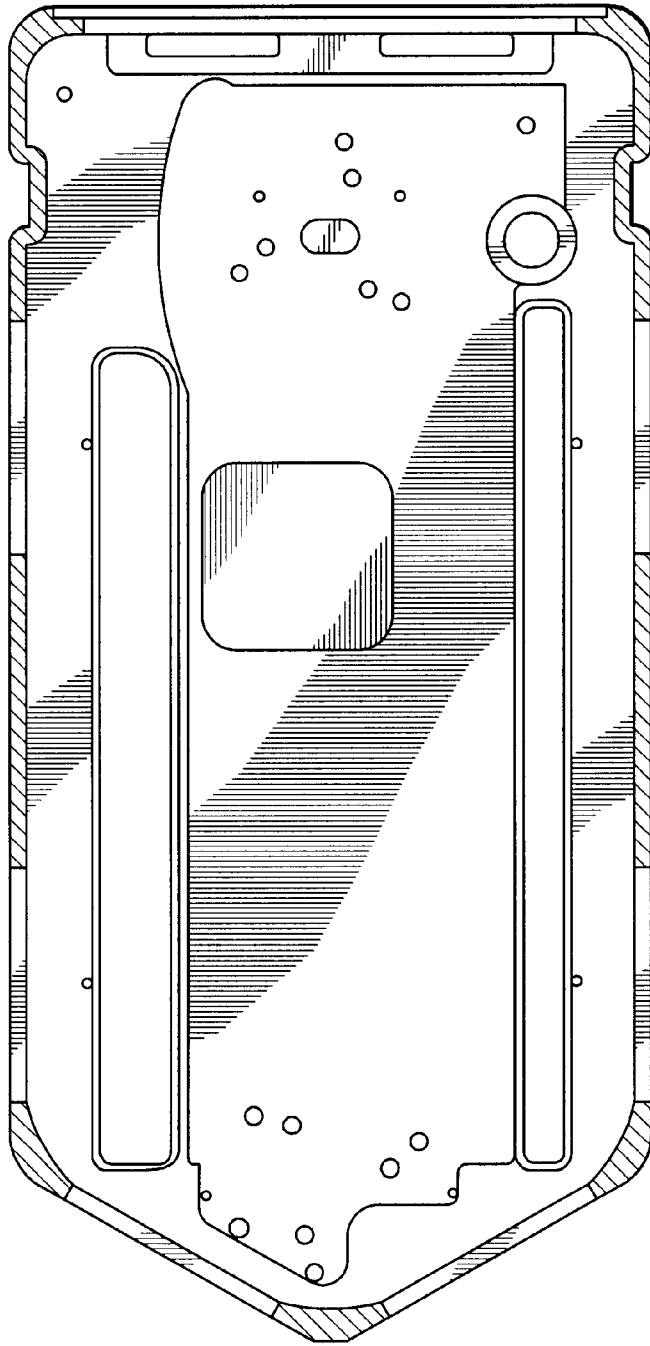


FIG. 9

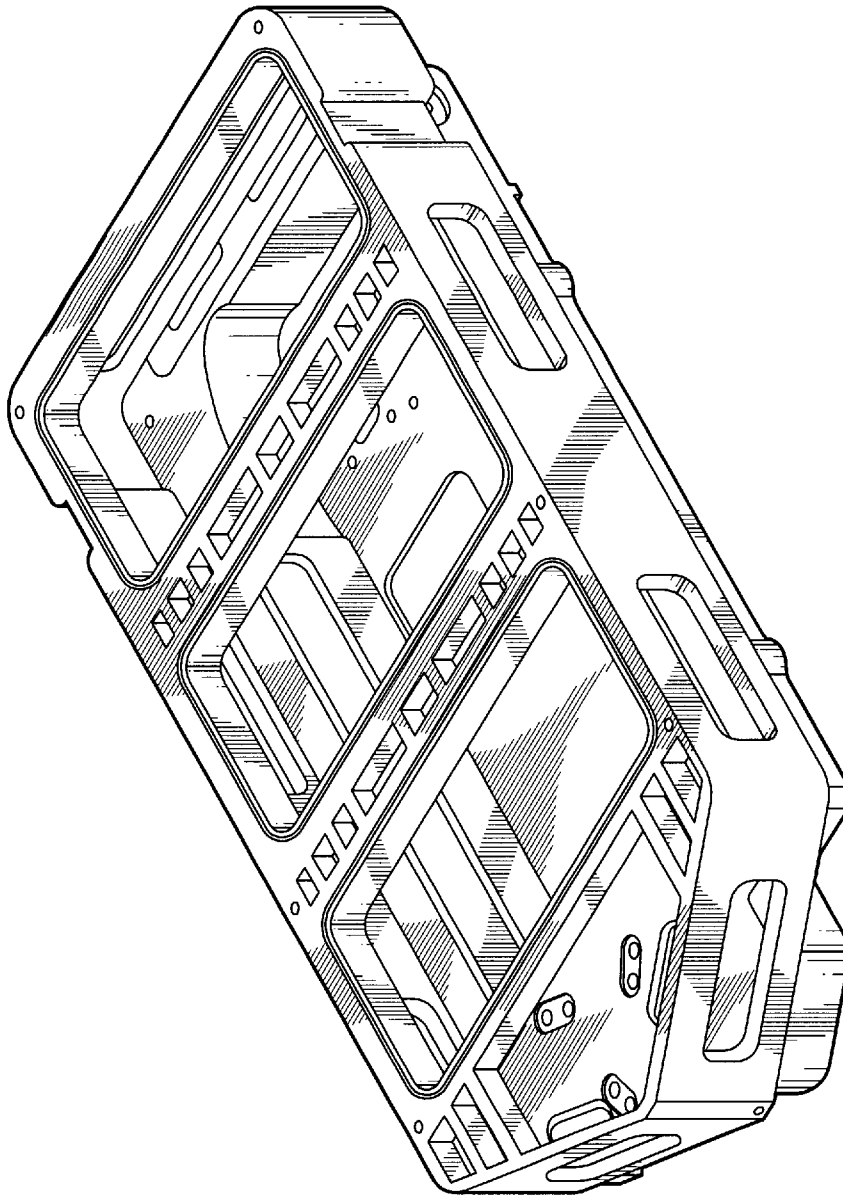


FIG.10

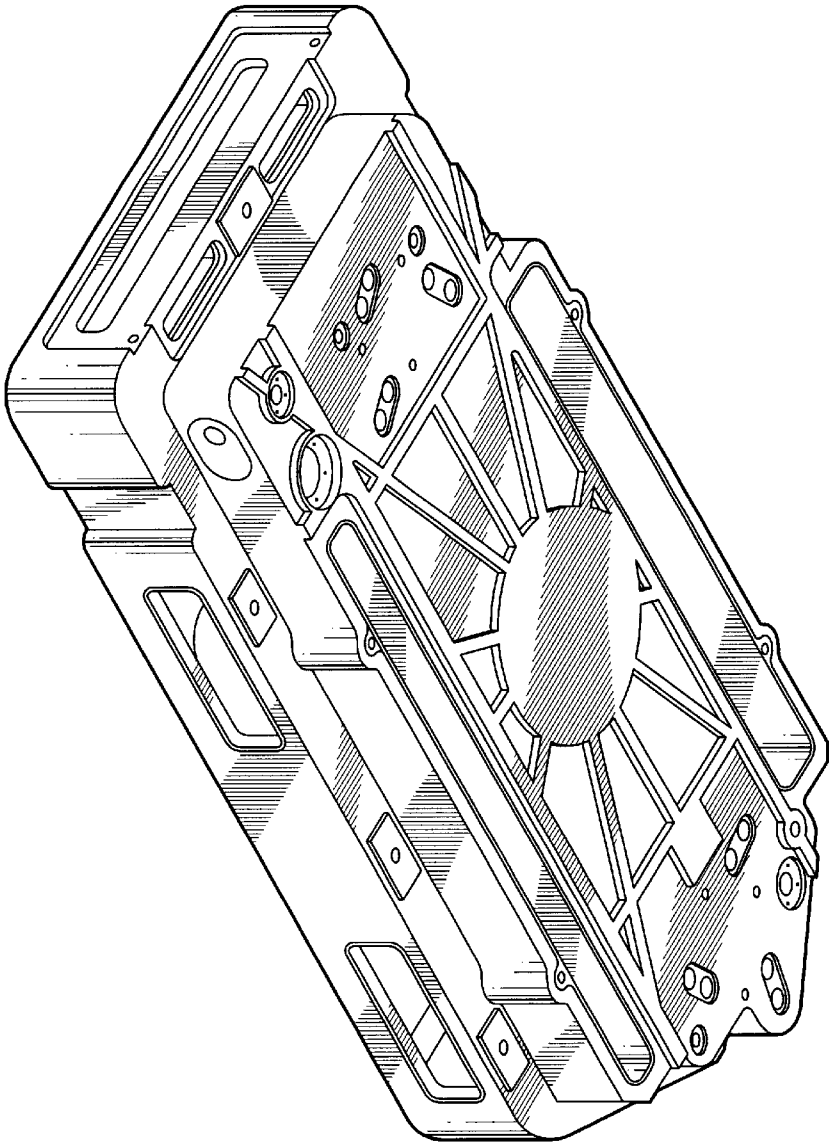


FIG.11